



Material Content Data Sheet



Sales Product Name		TLE8203E		Issued		4. September 2015		
MA#		MA001387212						
Package		PG-DSO-36-50		Weight*		609.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.642	1.42	1.42	14171	14171
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.75		7453	
wire	non noble metal	copper	7440-50-8	184.568	30.26	31.06	302629	310548
	noble metal	gold	7440-57-5	2.936	0.48	0.48	4814	4814
encapsulation	organic material	carbon black	1333-86-4	0.801	0.13		1313	
	plastics	epoxy resin	-	36.825	6.04		60381	
	inorganic material	silicondioxide	60676-86-0	362.648	59.45	65.62	594621	656315
leadfinish	non noble metal	tin	7440-31-5	5.508	0.90	0.90	9032	9032
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1297	1297
glue	plastics	epoxy resin	-	0.583	0.10		956	
	noble metal	silver	7440-22-4	1.748	0.29	0.39	2867	3823
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com